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54 **Shielded back plane connector.**

57 A shielded back plane connector comprises a header assembly (2) and a daughter board connector (4). The daughter board connector includes an upper and lower shield (22, 24) where the upper and lower shields (22, 24) include stamped windows (84) thereby forming passages for allowing structural ribs (32) of the housing to pass therethrough while providing a contact (82) for contact with grounding pins (48) disposed in the header assembly (2). A cross talk shield (100) can be positioned intermediate each of terminal sub-assemblies (20) thereby reducing the cross talk between adjacent terminals. The shield (100) includes a contact portion for contacting the centre terminal in the shielded sub-assembly (20), for using the centre terminal as a ground terminal.

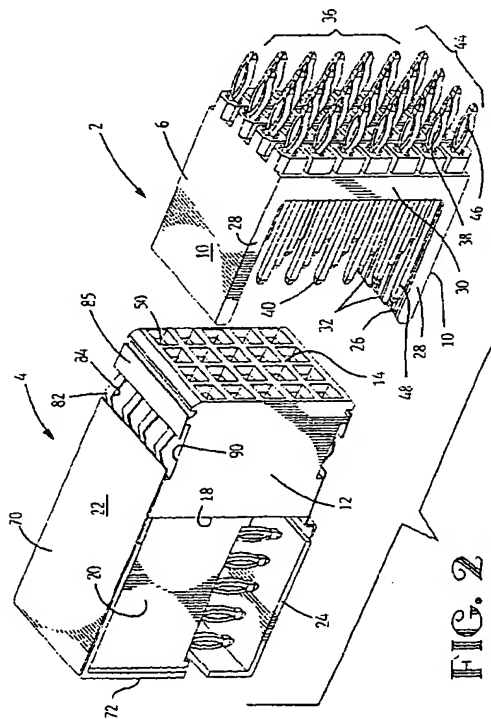
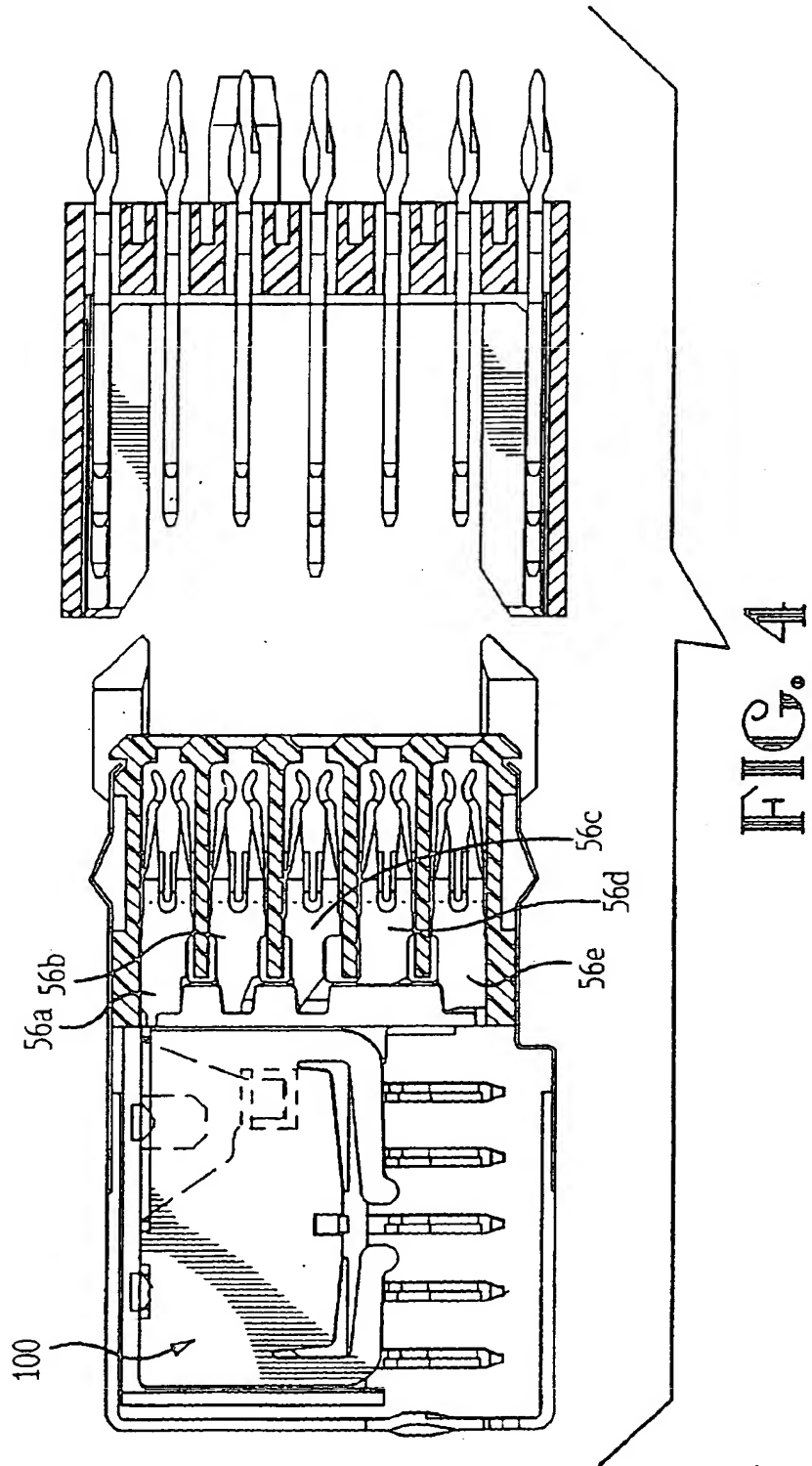


FIG. 2

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The subject invention relates to a shielded back plane connector which can be mounted to a back plane, which receives a shielded daughter card connector.

It is common in electronic architecture to provide for a header connector having a plurality of male pins to be mounted to a mother board connector. A daughter board connector is mounted to a daughter card and is profiled for receipt within the header connector, the daughter board connector having a plurality of receptacle sockets for electrical connection with the male pins in the header. It is also known to shield the mother board connector and the daughter board connector to improve their EMI/RFI characteristics for example, EP Patent application 0,422,785 shows such an assembly, where the shielded back plane connector can be interconnected to a shielded daughter board connector. One of the necessities which has been presented in this technology has been to reduce the size requirements of the overall packaged system.

The object of the invention then is to provide for a shielded back plane assembly having overall reduced dimensions, without compromising on other characteristics such as EMI/RFI, signal speed, and the like.

The objects were accomplished by providing a high density shielded back plane connector comprising a first insulative housing for mounting to a mother board comprising a header having two thin upstanding side walls, the header having a plurality of signal contacts within the header for mating with complementary contacts in a complementary connector. The thin side walls have strengthening ribs on an inside surface to rigidify the upstanding side walls and a plurality of ground contacts intermediate at least some of the strengthening ribs. A shielded daughter board connector is adapted to electrically mate with the mother board electrical connector, the daughter board comprising an insulative housing having a plurality of signal contacts adapted to mate with the mother board signal contacts. The daughter board further comprises an upper and lower shield member positioned over outer side walls of the daughter board housing, where each shield member includes an outwardly projecting kink along a front edge thereof, thereby forming a ground shield contact for mating with the ground tabs in the header. The ground shields include openings on opposite sides of the ground shield contacts, whereby the openings form a passage to receive the strengthening ribs therein while the ground shield contacts project between the ribs to make electrical contact with the header ground contacts.

Embodiments of the present invention will now be described by way of example with reference to the accompanying drawings in which:

Figure 1 is an isometric view of the shielded daughter board connector exploded from the

complementary header;

Figure 2 is an isometric view of an enlarged section of the connectors shown in Figure 1;

Figure 3 is a cross-sectional view through the connector of Figure 1 or 2 showing the internal structure thereof;

Figure 4 is a cross-sectional view similar to that of Figure 3 showing an alternate embodiment having a cross talk shield;

Figure 5 is a side plan view of the terminal sub-assembly for use in the embodiment of Figure 4;

Figure 6 is a cross-sectional view through lines 6-6 of Figure 5;

Figure 7 is a lower plan view of the terminal sub-assembly shown in Figure 5;

Figure 8 is a plan view of the cross talk shield in a stamped blank form;

Figure 9 is a side plan view showing the cross talk shield in place on the terminal sub-assembly;

Figure 10 shows a cross-sectional view of the terminal sub-assembly through lines 10-10; and

Figure 11 shows a lower plan view of two of the sub-assemblies stacked together with the cross talk shield in place.

Figure 1 is an isometric view of a header connector shown generally at 2 and a shielded daughter card connector shown generally at 4. The header assembly 2 is generally comprised of an insulating housing 6 having a lower surface 8 for mounting to a mother board and side walls 10 upstanding from the floor portion 8. With reference still to Figure 1, the daughter board connector 4 is generally comprised of a forward housing portion 12 having a front mating face 14 side surfaces 16 and a rear surface 18. A plurality of terminal sub-assemblies 20 are shown assembled to the housing 12 and encapsulated in upper and lower shield members 22, 24 respectively.

With reference now to Figure 2, the header assembly 2 and daughter board assembly will be described in greater detail, where Figure 2 is an enlarged section of the assemblies shown in Figure 1. As shown in Figure 2, the header housing 6 has side walls 10 comprised of thin side wall sections 26 having end strengthening ribs 28 and 30. Along the length of the thin side wall section 26, a plurality of strengthening ribs 32 are positioned integral with the sidewall 10 to rigidify these thin side wall sections. The header assembly 2 further comprises a plurality of signal contacts 36 having compliant pin portions 38 extending outwardly from the floor 8 and further include male pin portions 40 positioned within the header intermediate the side walls 10. The header assembly 2 further comprises a plurality of grounding contacts 44 having compliant pin portions 46 and a grounding pin portion 48 positioned between strengthening ribs 32.

With reference now to Figures 2 and 3, the daughter board connector 4 will be described in great-

er detail. Housing 12 includes a plurality of signal pin contact receiving openings shown at 50 leading into a terminal receiving passageway 52, the passageway 52 extending rearwardly to a face 54. A plurality of terminal subassemblies 20 are positioned against the housing 20 where each subassembly includes a plurality of electrical terminals 56 encapsulated in an overmoulded web of plastic material 58. Each contact 56 includes a receptacle portion 60 for mating contact with the male signal pins 40 and further comprises an intermediate portion 62 and compliant pin portions 64.

With reference again to Figure 2, the upper shield 22 includes an upper plate portion 70 for positioning above the housing portion 12 and above the terminal subassemblies 20. The upper shield member 22 further includes a rear plate portion 72 for positioning behind the terminal subassemblies 20, the rear plate portion 72 including a plurality of integral compliant pin sections 74 for mechanical and electrical connection to a printed circuit board 75, as shown in Figure 3. The upper shield member 22 further includes a thin plate portion 78 (Figure 3) formed by a premilling operation to reduce the thickness of the shield portion over the housing 20 to reduce the overall width dimension of the shielded data board connection. As shown in Figure 2, the upper shield 22 is kinked adjacent to the front mating face 14 to form projections 82 extending above the plane formed by the upper plate portion 70. A plurality of windows 84 are stamped from the upper plate portion 70 whereby the windows are laterally positioned to receive the strengthening ribs 32 therein, while the projections 82 form shield contacts, which span the strengthening ribs 32, for mating with the ground pins 48. To rigidify the plurality of shield contacts 82 a strengthening strap 85 extends transversely of the shields contacts 82 and is held to the housing by a folded front edge 86 positioned in a laterally extending groove 88 (Figure 3). To improve the resiliency of the shield contacts 82 a laterally extending channel 90 is positioned below the shield contacts 82. The lower shield member 24 is similar to the upper shield portion including a plate portion 95 having a thin wall section 96, shield contacts at 98, and compliant portions 99 for interconnection to the printed circuit board.

With reference now to Figure 4, the above mentioned daughter board connector 4 can alternatively be used with an additional shield placed intermediate the plurality of terminal sub-assemblies 20 to reduce the cross talk between the adjacent terminal strips. For this purpose, a cross talk shield 100 can be positioned between each adjacent stacked terminal sub-assembly 20. In the preferred embodiment of the invention the cross talk shield 100 contacts the center terminal 56C leaving terminals 56A, 56B and 56D, 56E for signal contacts thereby forming a modified strip line connector.

With reference now to Figure 5, the shielded sub-assembly 20 will be described in greater detail for use with the cross talk shield. As mentioned above, the terminal sub-assembly 20 has an overmoulded web of material 58 having a recessed surface at 102 and a raised surface 104. As shown in Figures 5 and 6, a window is formed at 106 exposing a portion of the central terminal 56C for contacting with the cross talk shield 100. With reference again to Figure 5, two apertures are formed through the insulating web 58 at 110 and a lower slot 112 is formed by two upstanding ribs 114 having a thickness equal to the raised portion 104 with the intermediate portion between the slot being recessed to the surface 102. With reference now to Figure 8, the cross talk shield 100 has a flat plate portion 120 including two lower contact arms 122 for contact with a trace on a printed circuit board, and further comprises an upper contact arm shown at 124. The cross talk shield 100 further comprises locking tabs 126 at an upper edge thereof, and locking tab 128 at a lower edge thereof. As shown in Figure 10, the cross talk shield is formed with the contact arm 124 bent around an upper edge of the flat plate portion 122, and the end of the contact arm 124 is formed with a radius section thereby forming a contact surface 126 for contacting the central contact 56C. Figure 10 also shows cross-talk shield positioned on the surface 104, with the cooperation between the tabs 126 within the openings 110, and shows the tab 128 frictionally held between the two upstanding ribs 114 in the slot thereof. As shown in Figures 10 and 11, a plurality of cross talk shields 100 can be placed against the terminal sub-assemblies 20 to reduce the cross talk between adjacent terminal sub-assemblies. The cross-talk shields can be added without increasing the stack thickness of the terminal sub-assemblies and the shields 100.

Advantageously then, as the center line distance between adjacent terminals in adjacent terminal sub-assemblies 20 has been reduced by half, by the addition of the cross talk shield 100, the impedance has been increased by the formation of the recessed surface 102, thereby providing a pocket of air adjacent to the terminals. Furthermore the ground signal path has been reduced by providing the contact arms 122 adjacent to the daughter board and by providing the contact to the centre terminal 56C.

Claims

1. A high density shielded backplane connector (2,4) comprising a first insulative housing (6) for mounting to a mother board, comprised of a header (2) having a plurality of signal contacts (36) within said header (2) for mating with complementary contacts in a complementary connector, and a plurality of grounding tabs (48), and

a shielded daughter board electrical connector (4) adapted to electrically mate with said mother board electrical connector (2), said daughter board connector (4) comprising an insulative housing (12) having a plurality of signal contacts (56) adapted to mate with said mother board signal contacts (36), said daughter board connector (4) further comprising an upper and lower shield member (22,24) positioned over outer side walls of said daughter board housing (12), having shield contacts which mate with ground contacts in said header (2), characterized in that said header housing (6) has two thin upstanding side-walls (10) which have strengthening ribs (32) on an interior surface thereof, laterally spaced along the length thereof to rigidify said thin walls (10), with said grounding tabs (48) being positioned between at least some of said strengthening ribs (32), and in that each said shield member (22,24) includes outwardly directed shield contacts (82) with openings (84) on opposite sides of said contacts for receiving said ribs (32).

2. The backplane connector of claim 1, characterized in that said shield contacts are defined by outwardly projecting kinks (982) along a front edge thereof, thereby forming ground shield contracts for mating with the grounding tabs (48) in said header (2), said openings (84) forming a passage to receive said strengthening ribs (32) to make electrical contact with said header ground contacts (48).
3. The backplane connector of claim 1 or 2, wherein said openings are formed by stamping windows (84) through said shield members (22,24).
4. The backplane connector of any of claims 1-3, wherein said upper and lower shield members (22,24) include a strap portion (85) extending transversely of said openings.

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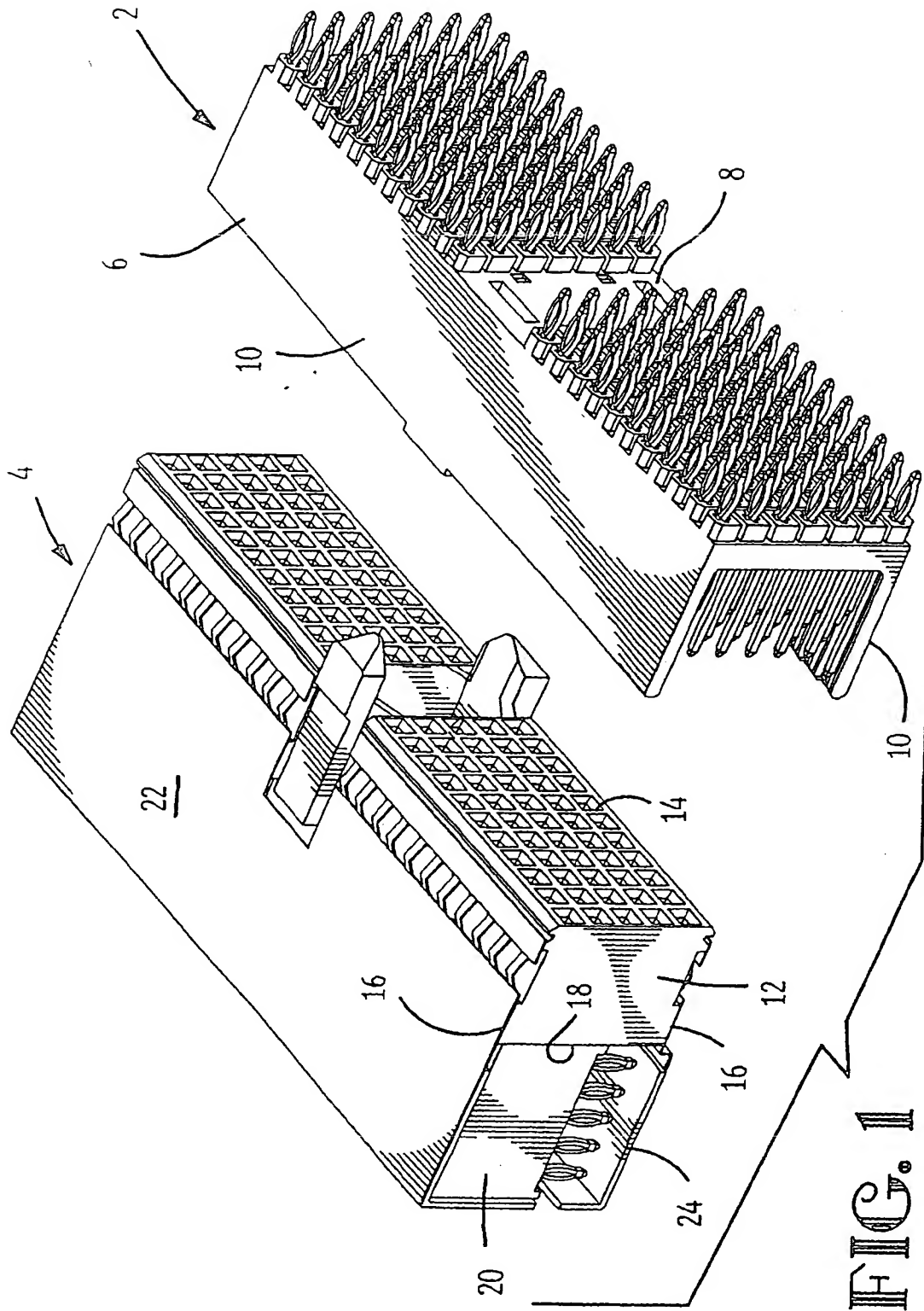
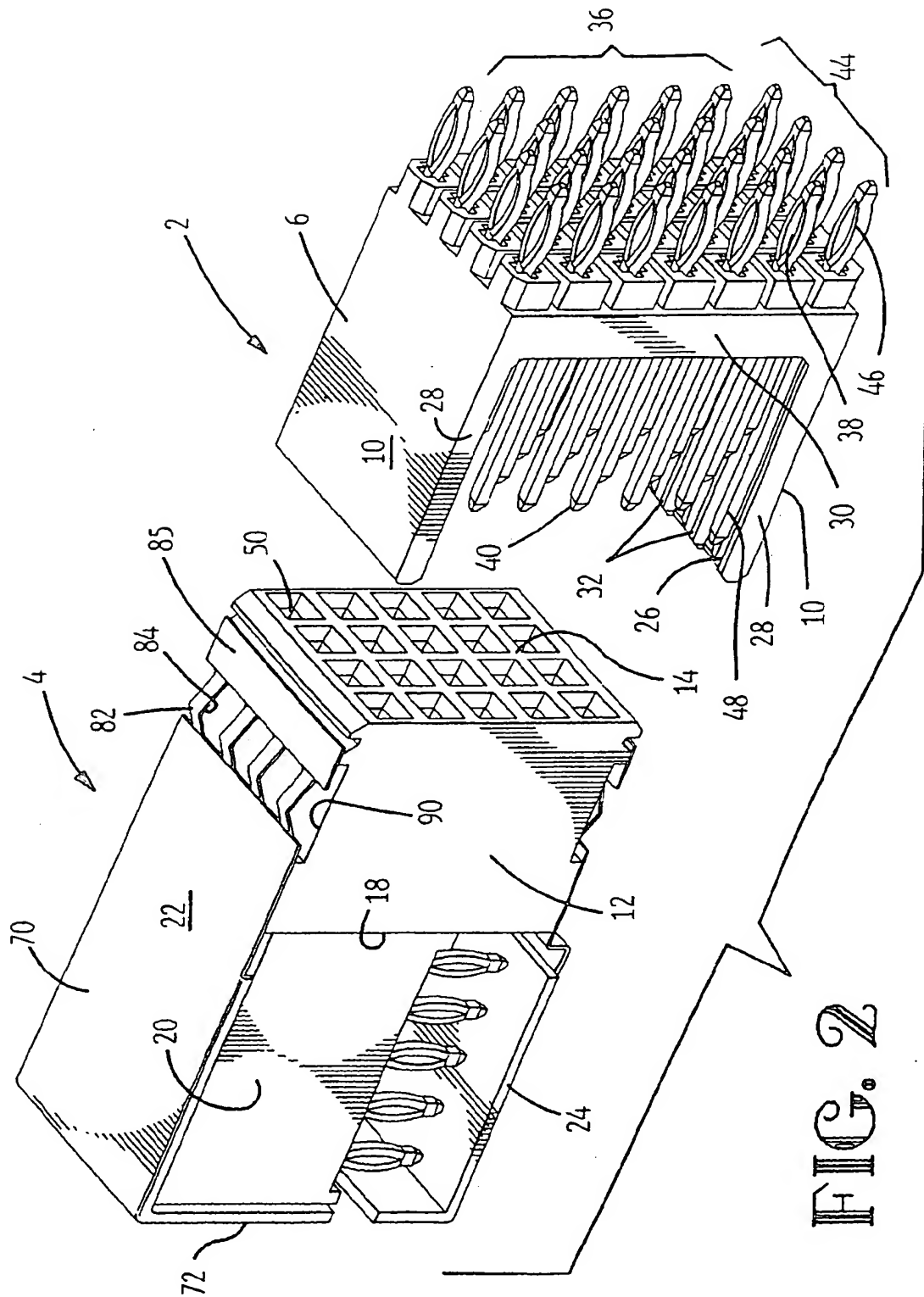


FIG. 1



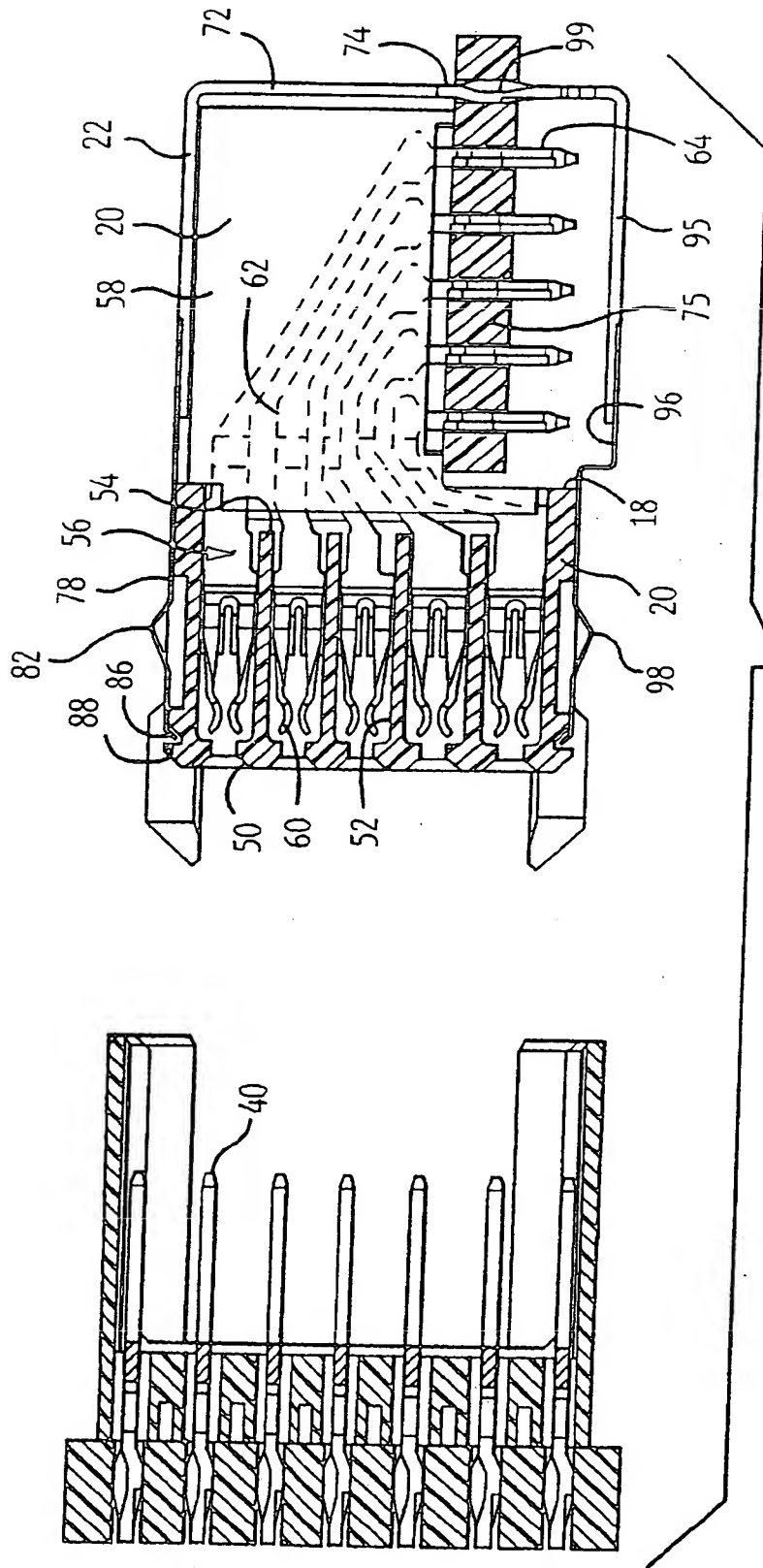


FIG. 3

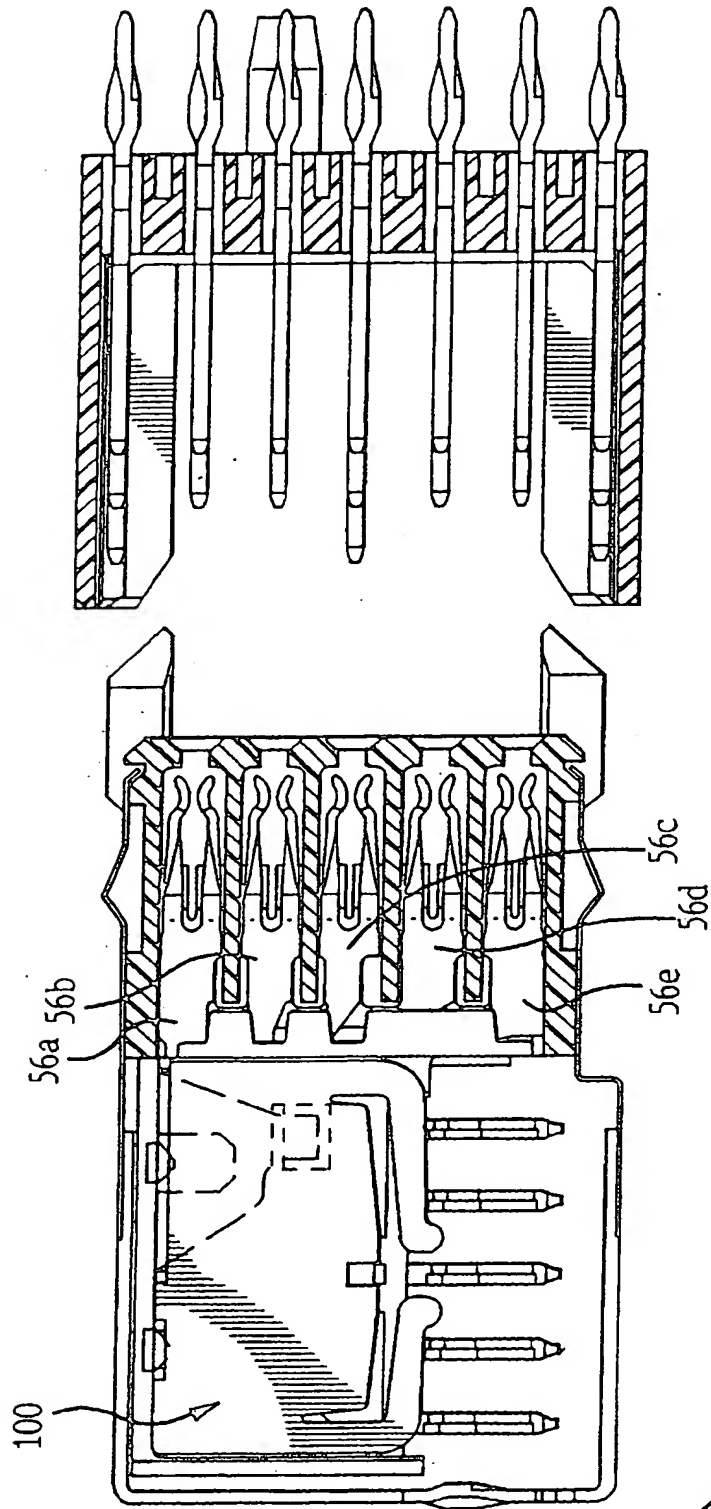


FIG. 4

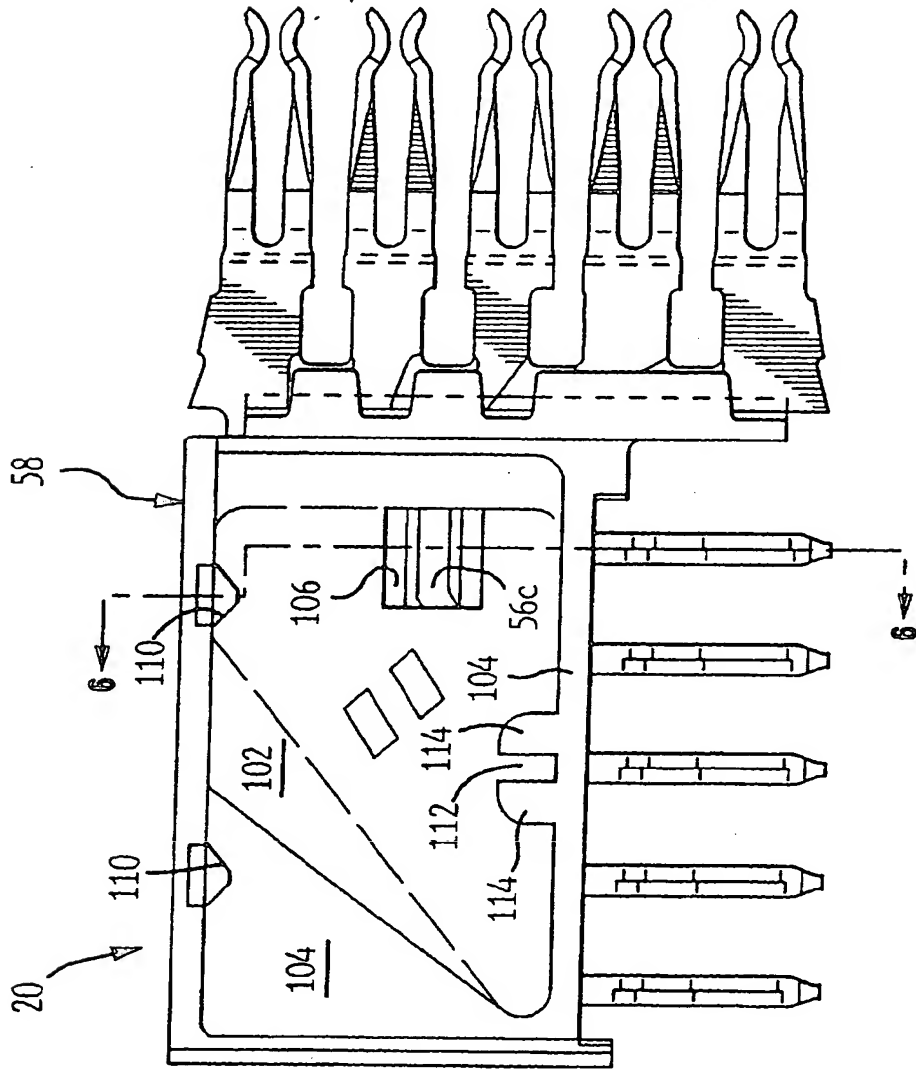


FIG. 5

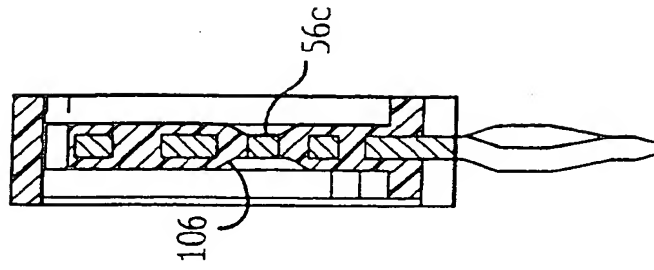


FIG. 6

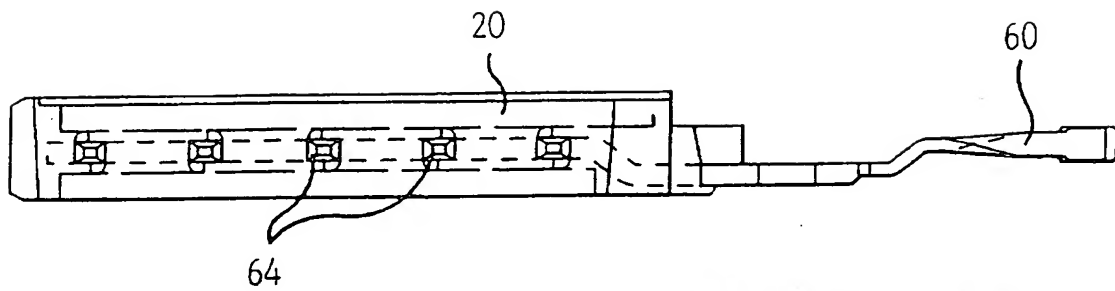


FIG. 7

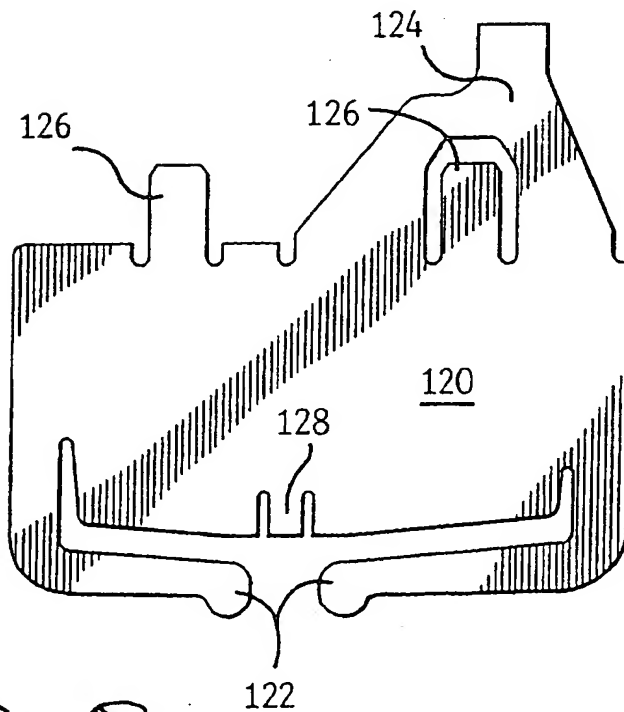


FIG. 8

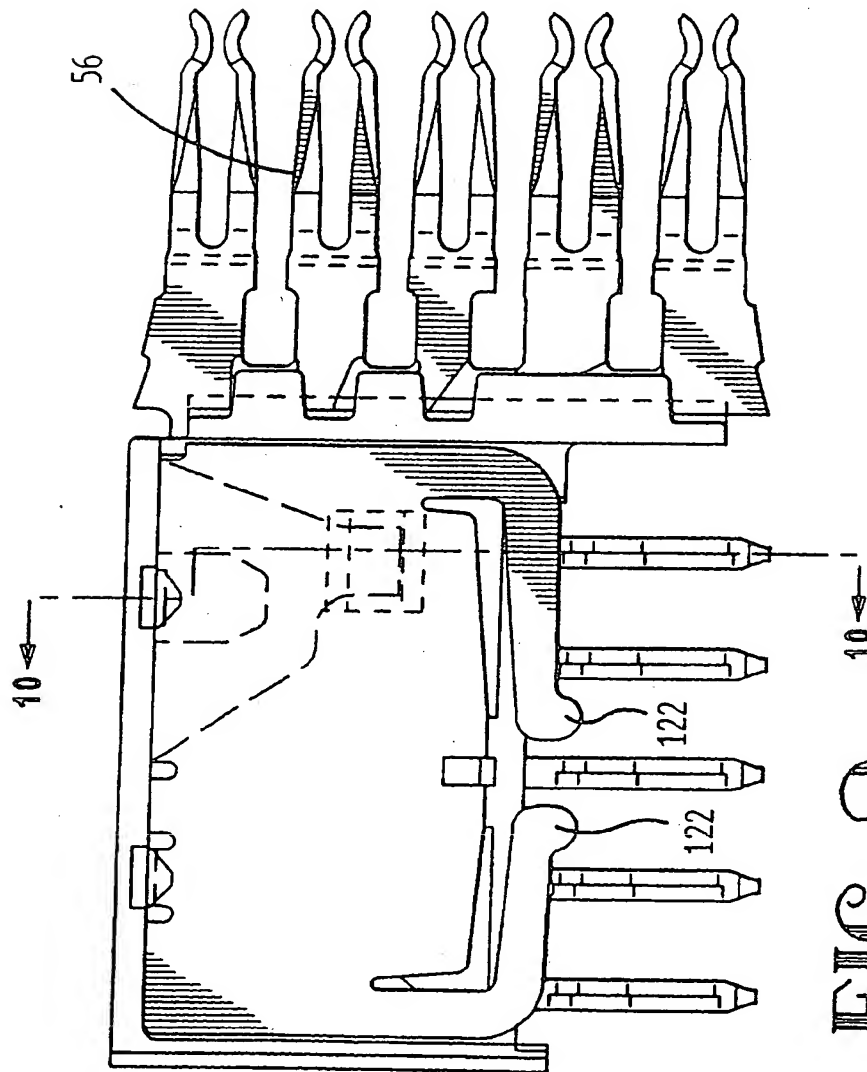


FIG. 9

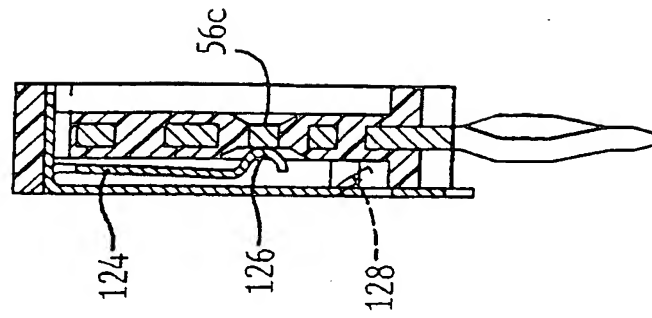


FIG. 10

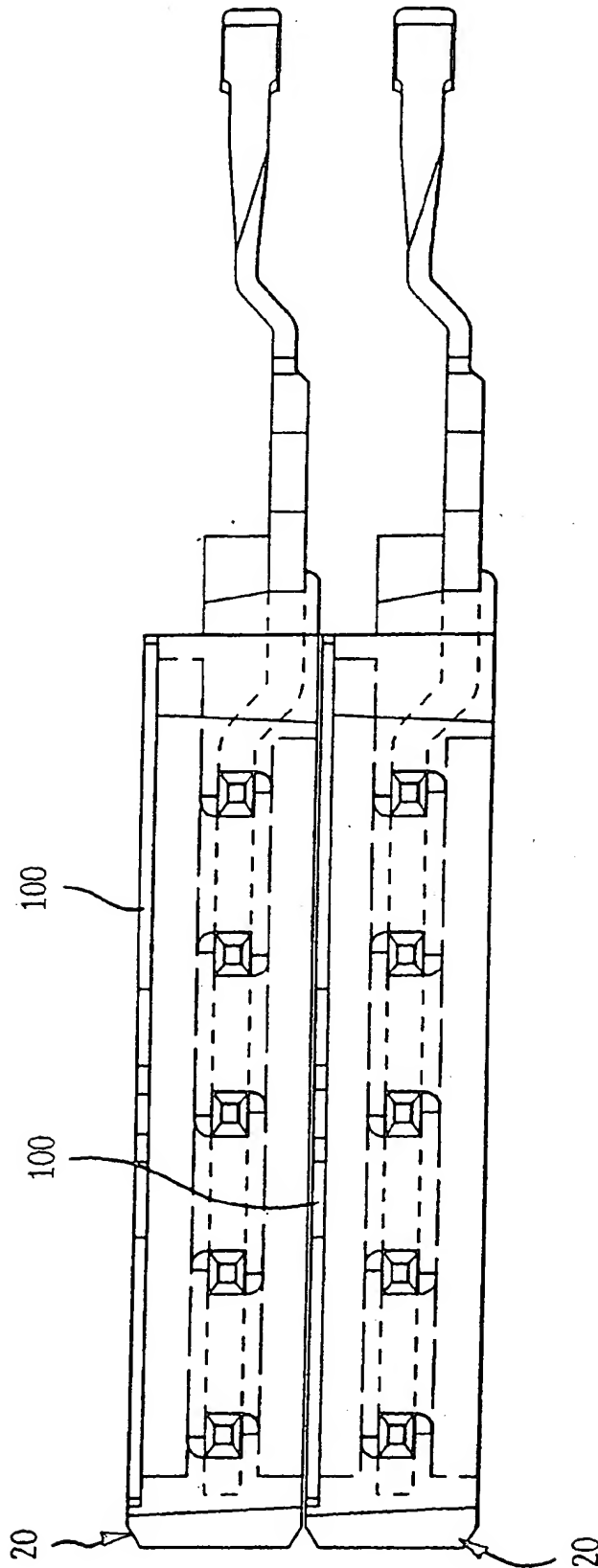


FIG. 11



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EUROPEAN SEARCH REPORT

Application Number

EP 93 30 1726

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.5)
A	GB-A-2 163 305 (TERADYNE INC.) * page 1, line 93 - page 2, line 11; figures 3-5 *	1	H01R13/658 H01R23/70 H01R23/68
A	EP-A-0 347 097 (AMP INC.) * column 3, line 17 - line 27; figure 4 *	1	
P,A	US-A-5 137 472 (HILLBISCH ET AL.) * column 1, line 66 - column 2, line 24; figure 3 *	1	
			TECHNICAL FIELDS SEARCHED (Int. Cl.5)
			H01R
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 09 JUNE 1993	Examiner HORAK A.L.
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